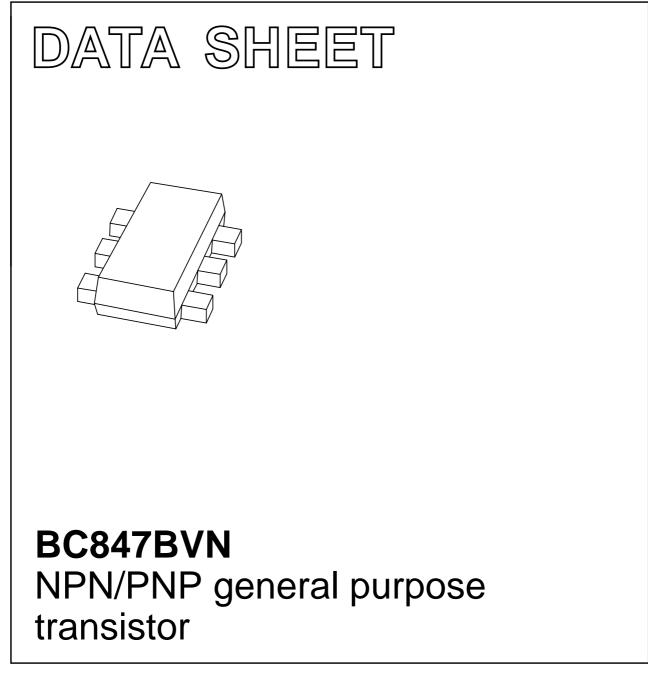
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Aug 30 2001 Nov 07



FEATURES

- 300 mW total power dissipation
- Very small 1.6 mm x 1.2 mm ultra thin package
- Excellent coplanarity due to straight leads
- Replaces two SC-75/SC-89 packaged transistors on same PCB area
- Reduced required PCB area
- Reduced pick and place costs.

APPLICATIONS

- General purpose switching and amplification
- Switch mode power supply complementary MOSFET driver
- Complementary driver for audio amplifiers.

DESCRIPTION

NPN/PNP transistor pair in a SOT666 plastic package.

MARKING

TYPE NUMBER	MARKING CODE		
BC847BVN	13		

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

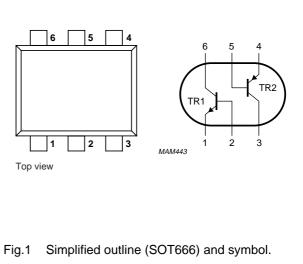
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transistor; for the PNP transistor with negative polarity					
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	-	45	V
V _{EBO}	emitter-base voltage	open collector	-	5	V
I _C	collector current (DC)		-	100	mA
I _{CM}	peak collector current		-	200	mA
I _{BM}	peak base current		-	200	mA
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C;$ note 1	-	200	mW
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C
Per device)				
P _{tot}	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$; note 1	-	300	mW

PINNING

Note

1. Transistor mounted on an FR4 printed-circuit board.

PINDESCRIPTION1, 4emitterTR1; TR22, 5baseTR1; TR26, 3collectorTR1; TR2



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THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	notes 1 and 2	416	K/W	

Notes

- 1. Transistor mounted on an FR4 printed-circuit board.
- 2. The only recommended soldering is reflow soldering.

CHARACTERISTICS

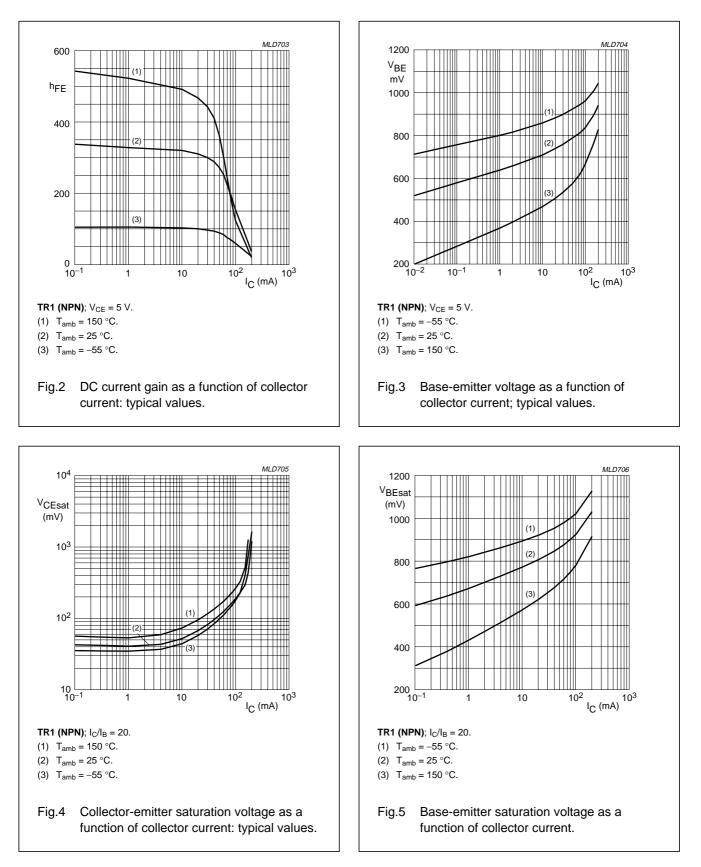
 T_{amb} = 25 $^\circ C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transis	Per transistor; for the PNP transistor with negative polarity					
I _{CBO}	collector-base cut-off current	$V_{CB} = 30 \text{ V}; \text{ I}_{E} = 0$	-	-	15	nA
		$V_{CB} = 30 \text{ V}; \text{ I}_{E} = 0; \text{ T}_{j} = 150 ^{\circ}\text{C}$	_	-	5	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 \text{ V}; \text{ I}_{C} = 0$	-	-	100	nA
h _{FE}	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 2 \text{ mA}$	200	_	450	
V _{CEsat}	collector-emitter saturation	I _C = 10 mA; I _B = 0.5 mA	-	_	100	mV
voltage	$I_{C} = 100 \text{ mA}; I_{B} = 5 \text{ mA}; \text{ note } 1$	-	-	300	mV	
V _{BEsat}	collector-emitter saturation voltage	$I_{\rm C}$ = 10 mA; $I_{\rm B}$ = 0.5 mA	-	755	-	mV
f _T	transition frequency	I _C = 10 mA; V _{CE} = 5 V; f = 100 MHz	100	_	_	MHz
NPN trans	istor			•		
V _{BE}	base-emitter turn-on voltage	$V_{CE} = 5 \text{ V}; I_{C} = 2 \text{ mA}$	580	655	700	mV
C _c	collector capacitance	$V_{CB} = 10 \text{ V}; I_E = I_e = 0; f = 1 \text{MHz}$	_	-	1.5	pF
Ce	emitter capacitance	$V_{EB} = 500 \text{ mV}; I_C = I_c = 0; f = 1 \text{MHz}$	_	11	_	pF
PNP trans	istor			•		•
V _{BE}	base-emitter turn-on voltage	$V_{CE} = -5 \text{ V}; \text{ I}_{C} = -2 \text{ mA}$	600	655	750	mV
C _c	collector capacitance	$V_{CB} = -10 \text{ V}; \text{ I}_{C} = \text{ I}_{c} = 0; \text{ f} = 1 \text{ MHz}$	-	-	2.2	pF
C _e	emitter capacitance	$V_{EB} = -500 \text{ mV}; I_E = I_e = 0; f = 1 \text{MHz}$	-	10	-	pF

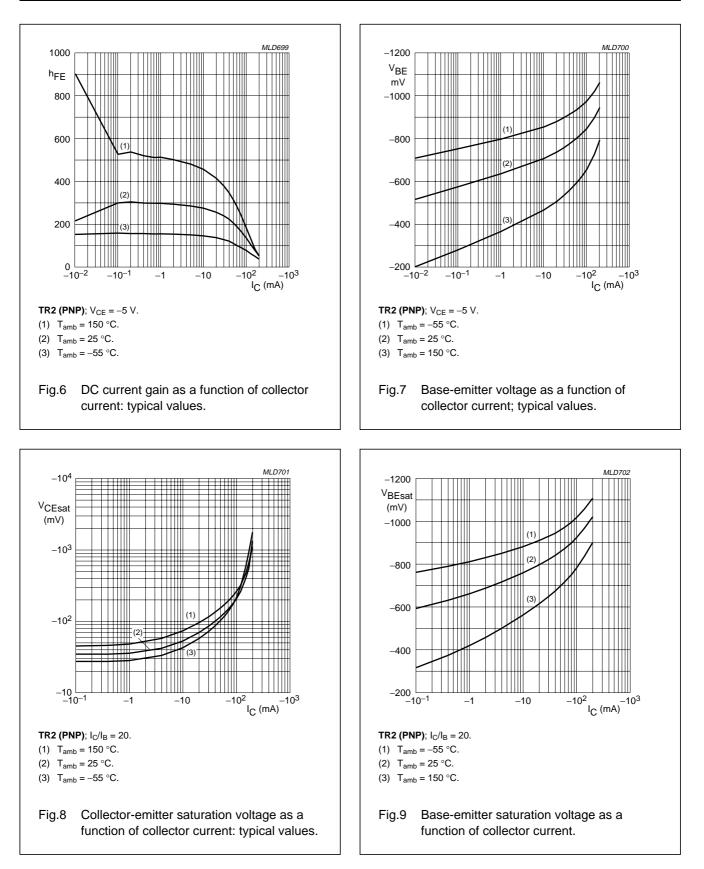
Note

1. Pulse test: $t_p \le 300 \ \mu s$; $\delta \le 0.02$.

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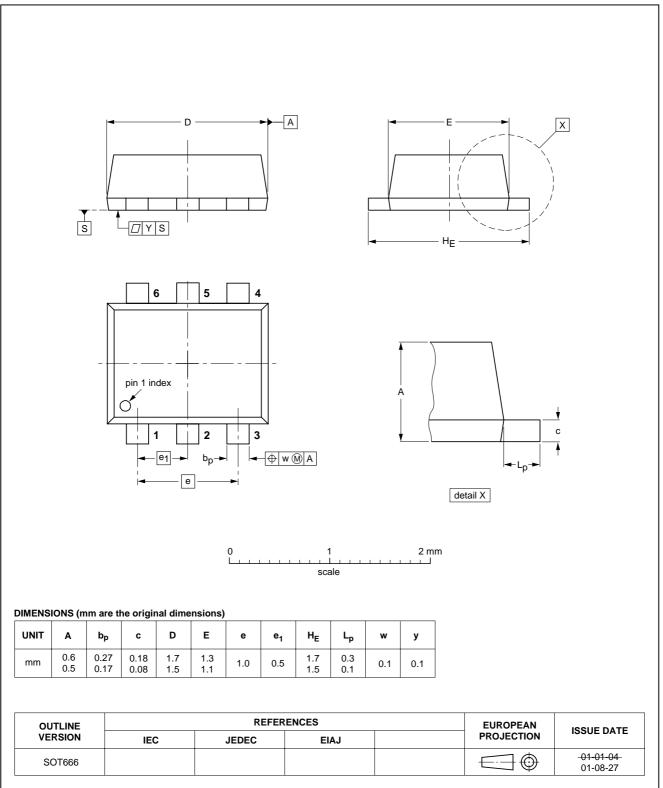


BC847BVN

NPN/PNP general purpose transistor

PACKAGE OUTLINE

Plastic surface mounted package; 6 leads



SOT666

BC847BVN

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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